



Declaration of Conformity to EU RoHS Directive 2011/65/EU

GE Power Electronics Part Number:	108457706
Product Description:	JW150G1

This is to certify that the parts/products listed above meet the following materials requirements of the **RoHS Directive 2011/65/EU**, as amended.

The part numbers above that GE Power Electronics has identified as RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annex of the RoHS Directive. Note that any exemptions taken in this case would not include application specific exemptions (e.g. RoHS exemption 7b -lead in solder for network infrastructure) as GE Power Electronics cannot determine where products will be used.

GE Power Electronics is also very aware of the REACH initiative and the SVHC candidate list. We have examined our component database and have determined that the product listed above is compliant with the REACH Directive as of the date of this Compliance Statement.

GE Power Electronics assumes no responsibility to determine whether Customer's use of these products is covered under any RoHS exemptions.

The above information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreement terms between GE Power Electronics (or its affiliated companies) and its customers.

EU RoHS Restricted Substance	Allowable Limit (at homogenous material level)
Cadmium and its compounds	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE)	1000 ppm (0.1 weight %)

Parts/products exceeding the allowable limits at the homogeneous material level rely exclusively on the exemption(s) identified below:

Note: Exemptions in italics have expired per the EU RoHS Directive and are no longer applicable.

1. Mercury in single capped (compact) fluorescent lamps not exceeding (per burner):

- (a) For general lighting purposes < 30 Watts
- (b) For general lighting purposes \geq 30 Watts and < 50 Watts
- (c) For general lighting purposes \geq 50 Watts and < 150 Watts
- (d) For general lighting purposes \geq 150 Watts: 15 mg
- (e) For general lighting purposes with circular or square structural shape and tube diameter \leq 17 mm
- (f) For special purposes: 5 mg

2a. Mercury in double-capped linear fluorescent lamps for general lighting purposes not exceeding (per lamp):



- (1) Tri-band phosphor with normal lifetime and a tube diameter < 9 mm (e.g. T2)
- (2) Tri-band phosphor with normal lifetime and a tube diameter ≥ 9 mm and ≤ 17 mm (e.g. T5)
- (3) Tri-band phosphor with normal lifetime and a tube diameter > 17 mm and ≤ 28 mm (e.g. T8)
- (4) Tri-band phosphor with normal lifetime and a tube diameter > 28 mm (e.g. T12)
- (5) Tri-band phosphor with long lifetime ($\geq 25,000$ h)

2b. Mercury in other fluorescent lamps not exceeding (per lamp):

- (1) Linear halophosphate lamps with tube diameter > 28mm (e.g. T10 and T12): 10 mg
- (2) Non-linear halophosphate lamps (all diameters): 15mg
- (3) Non-linear tri-band phosphor lamps with tube diameter > 17 mm (e.g. T9)
- (4) Lamps for other general lighting and special purposes (e.g. induction lamps)

3. Mercury in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) for special purposes not exceeding (per lamp):

- (a) Short length (≤ 500 mm)
- (b) Medium length (> 500 mm and ≤ 1500 mm)
- (c) Long length (> 1500 mm)

4a. Mercury in other low pressure discharge lamps (per lamp)

4b. Mercury in High Pressure Sodium (vapor) lamps for general lighting purposes not exceeding (per burner) in lamps with improved color rendering index $R_a > 60$:

- (I) $P \leq 155$ W
- (II) $155 < P \leq 405$ W
- (III) $P > 405$ W

4c. Mercury in other High Pressure Sodium (vapor) lamps for general lighting purposes not exceeding (per burner):

- (I) $P \leq 155$ W
- (II) $155 < P \leq 405$ W
- (III) $P > 405$ W

4d. Mercury in High Pressure Mercury (vapor) lamps (HMPV)

4e. Mercury in metal halide lamps (MH)

4f. Mercury in other discharge lamps for special purposes not specifically mentioned in Annex

5a. Lead in glass of cathode ray tubes

5b. Lead in glass of fluorescent tubes not exceeding 0.2% by weight

6a. Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight

6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight

6c. Copper alloy containing up to 4% lead by weight

7a. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)

7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications

7c-I. Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

7c-II. Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher

7c-III. Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC

8a. Cadmium and its compounds in one shot pellet type thermal cut-offs



8b. Cadmium and its compounds in electrical contacts

9. Hexavalent chromium as an anticorrosion agent of the carbon steel cooling system in absorption refrigerators up to 0.75% by weight in the cooling solution

9b. Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications

11a. Lead used in C-press compliant pin connector systems

11b. Lead used in other than C-press compliant pin connector systems

12. Lead as a coating material for the thermal conduction module C-ring

13a. Lead in white glasses used for optical applications

13b. Cadmium and lead in filter glasses and glasses used for reflectance standards

14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

16. Lead in linear incandescent lamps with silicate coated tubes

17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications

18a. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as specialty lamps for diazoprinting reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba) 2MgSi2O7:Pb)

18b. Lead as activator in the fluorescent powder (1% lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb)

19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL)

20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCDs)

21. Lead and cadmium in printing inks for the application of enamels on glasses, such as borosilicate and soda lime glasses

23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm and less

24. Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors

25. Lead oxide in surface conduction electron emitter displays (SED) used in structural elements, notably in the seal frit and frit ring

26. Lead oxide in the glass envelope of Black Light Blue lamps

27. Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125dB SPL and above) loudspeakers

29. Lead bound in crystal glass as defined in Annex I (Categories 1, 2, 3 and 4) of Council Directive 69/493/EEC



30. Cadmium alloys as electrical/mechanical solder joints to electrical conductors located directly on the voice coil in transducers used in high-powered loudspeakers with sound pressure levels of 100 dB (A) and more

31. Lead in soldering materials in mercury free flat fluorescent lamps (which e.g. are used for liquid crystal displays, design or industrial lighting)

32. Lead oxide in seal frit used for making window assemblies for Argon and Krypton laser tubes

33. Lead in solders for the soldering of thin copper wires of 100 μm diameters and less in power transformers

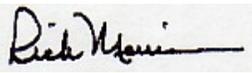
34. Lead in cermet-based trimmer potentiometer elements

36. Mercury used as a cathode sputtering inhibitor in DC plasma displays with a content up to 30 mg per display until 1 July 2010

37. Lead in the plating layer of high voltage diodes on the basis of a zinc borate glass body

38. Cadmium and cadmium oxide in thick film pastes used on aluminum bonded beryllium oxide

39. Cadmium in color converting II-VI LEDs ($< 10 \mu\text{g Cd per mm}^2$ of light-emitting area) for use in solid state illumination or display systems until 1 July 2014

Signature:  _____ Date: 3/06/2013 _____

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